

Part of #2

Sheet 1 of 1

Form 1449*	Atty. Docket No.: 884.523US1	Serial No. Unknown
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Madhav Datta et al.	PTO 621 U 09/96 1036
	Filing Date: Herewith	Group: Unknown 09/21/01

U.S. PATENT DOCUMENTS

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FOREIGN PATENT DOCUMENTS

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OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

EK	Annala, P., et al., "Electroplated Solder Alloys for Flip Chip Interconnections", <u>Physica Scripta</u> , T69, pp. 115-118, (1997)
EK	Datta, M., et al., "Electrochemical Fabrication of Mechanically Robust PbSn C4 Interconnections", <u>Journal of the Electrochemical Society</u> , 142 (11), 7 p., (Nov. 1995)
EK	Honma, S., et al., "Effectiveness of Thin-film Barrier Metals for Eutectic Solder Bumps", <u>Microelectronics International</u> , 14 (3), pp. 47-50, (Sept. 1997) -
EK	Liu, C.Y., et al., "Electron microscopy study of interfacial reaction between eutectic SnPb and Cu/Ni(V)/Al thin film metallization", <u>Journal of Applied Physics</u> , 86 (11), pp. 1-5, (Dec. 1999)

Examiner <u>En Kan</u>	Date Considered 10/31/02
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*Substitute Disclosure Statement Form (PTO-1449)

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